

IN THE SPECIFICATION:

Please replace the paragraph at page 7, lines 9-21 with the following amended paragraph:

Figure 2 is a cross sectional view of one embodiment of an apparatus 20 for depositing and planarizing a metal layer on a substrate 22. One example of an apparatus that may be adapted to benefit from the invention is an ELECTRA™ electroplating tool, available from Applied Materials, Inc., of Santa Clara, California. An example of a suitable electroplating tool is described by *Dordi et al.* in co-pending U.S. Patent application Serial No. 09/289,074, Patent No. 6,258,220, filed on April 8, 2000 1999, assigned to common assignee Applied Materials, Inc., and which is incorporated by reference herein to the extent not inconsistent with the invention. The apparatus 20 generally includes a carrier head assembly 30 movably supported by a stanchion 80 over a partial enclosure 34. The stanchion 80 and enclosure 34 are generally disposed on a common base 82. The stanchion 80 generally includes a base support 84 and a lift mechanism 86. The base support 84 extends perpendicularly from the base 82 and may be rotatable on its axis so that the carrier assembly 30 may be moved over the partial enclosure 34 or to other positions, for example, to other enclosures or to interface with other processing systems not shown.

Please replace the paragraph at page 17, lines 13-22 with the following amended paragraph:

In one embodiment, the transfer station 1022 comprises at least an input buffer station 1028, an output buffer station 1030, a transfer robot 1032, and a load cup assembly 1024. The loading robot 1010 places the substrate 22 onto the input buffer station 1028. The transfer robot 1032 has two gripper assemblies, each having pneumatic gripper fingers that grab the substrate 22 by the substrate's edge. The transfer robot 1032 lifts the substrate 22 from the input buffer station 1028 and rotates the gripper and substrate 22 to position the substrate 22 over the load cup assembly

1034, then places the substrate 22 down onto the load cup assembly 1024. An example of a transfer station that may be used to advantage is described by *Tobin* in United States Patent Application ~~09/314,771~~ 09/914,771, Patent No. 6,156,124, filed on October 40 6, 1999, assigned to common assignee Applied Materials, Inc., and which is hereby incorporated by reference.